

**INFORMATION DISCLOSURE STATEMENT
BY APPLICANT**

Attorney Docket Number	23-69853-01
Application Number	10/727,062
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First Named Inventor	John G. DeSteele
Art Unit	1795
Examiner Name	Jeffrey Thomas Barton

U.S. PATENT DOCUMENTS

Copies of U.S. Patent documents do not need to be provided, unless requested by the Patent and Trademark Office. For patents, provide the patent number and the issue date. For published U.S. applications, provide the publication number and the publication date. For unpublished pending patent applications, provide the application number and the filing date.

Examiner's Initials*	Cite No. (optional)	Number	Publication Date	Name of Applicant or Patentee

FOREIGN PATENT DOCUMENTS

Examiner's Initials*	Cite No. (optional)	Country	Number	Publication Date	Name of Applicant or Patentee

Examiner's Initials*	Cite No. (optional)	OTHER DOCUMENTS
		Bergstresser, T.R. et al., "Copper on Polyimide Flexible Substrate for Ultra-Thin, High Performance Applications," 4 pages (2000).
		Final Office action from the U.S. Patent and Trademark Office for U.S. Patent Application No. 10/726,744, dated February 29, 2008.
		International Search Report and Written Opinion for PCT/US2004/040460, filed December 2, 2004 (mailed March 7, 2006).
		Stölzer, M. et al., "Optimisation of p - (Bi _{0.25} Sb _{0.75}) ₂ Te ₃ and n - Bi ₂ (Te _{0.9} Se _{0.1}) ₃ Films for Thermoelectric Thin Film Components," 2nd Symposium on Thermoelectrics-Materials, Processing Techniques & Applications, 5 pages (1994).

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* Examiner: Initial if reference considered, whether or not in conformance with MPEP 609. Draw line through cite if not in conformance and not considered. Include copy of this form with next communication to applicant.